

MULTI-ROW BOARD-TO-BOARD CONNECTOR

Enhances design flexibility for **high-density** connections with our **automotive-compliant**, stackable connector designed with **snap-in biscuit design**, allowing for cost savings.



HIGHLY CONFIGURABLE

- Multiple connector units can be stacked together, with pin and board spacing options.



PLUGGABLE AND RELIABLE

- Very low levels of contact resistance ($<1\text{m}\Omega$).



AUTOMOTIVE-COMPLIANT

- Conforms to automotive performance requirements.
- Meet IEC60352-5 and IPC-9797 standards.

INTERPLEX 0.4 MINIPLX™ WITH INDICOAT™ PLATING

- Current rating:** 3 Amps/pin
- Option for IndiCoat™, Interplex's proprietary whisker mitigation plating technology

4 TO 30 CIRCUITS PER ROW; 1 TO 6 ROWS

- 1.8mm pin-to-pin spacing with 2mm row-to-row spacing

7MM TO 30MM BOARD TO BOARD SPACING

HIGH PERFORMANCE MATERIAL

- Relative humidity (RH):** 80% to 100%, 8-hour cycling
- Working temperature range:** -40°C to $+150^{\circ}\text{C}$
- Mechanical shock:** 35g for 5 to 10ms across 10 axes
- Vibration:** 8 hour per axis
- Voltage:** 500V DC $\pm 10\%$
- Insulation resistance:** $\geq 100\text{ M}\Omega$

